



CP 2826

#6

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

APPLICANT: OH ET AL. DOCKET NO.: WK2K1070  
SERIAL NO: 10/015,374 EXAMINER: WILLIAMS  
FILED: 12/12/2001 ART UNIT: 2826  
TITLE: STACKING STRUCTURE OF SEMICONDUCTOR CHIPS AND  
SEMICONDUCTOR PACKAGE USING IT.

RECEIVED  
OCT 30 2002  
TECHNOLOGY CENTER 2800

Assistant Commissioner  
for Patents  
Washington, D.C. 20231

Weiss & Moy, P.C.  
4204 North Brown Avenue  
Scottsdale, Arizona 85251-3989

October 24, 2002

I hereby certify that on the 24<sup>th</sup> day of October, 2002,  
this correspondence is being deposited with the U.S.  
Postal Service as first class mail in an envelope  
addressed to: Assistant Commissioner for Patents,  
Washington, D.C. 20231.

  
Jeffrey D. Moy

Dear Sir:

**AMENDMENT LETTER**

This is in response to the Office Action dated September 27,  
2002 in regards to the above identified patent application. Please  
amend the subject patent application as follows: